

**MOC8101
MOC8105
CNY17F-1**

**MOC8102
MOC8106
CNY17F-2**

**MOC8103
MOC8107
CNY17F-3**

**MOC8104
MOC8108
CNY17F-4**

FEATURES

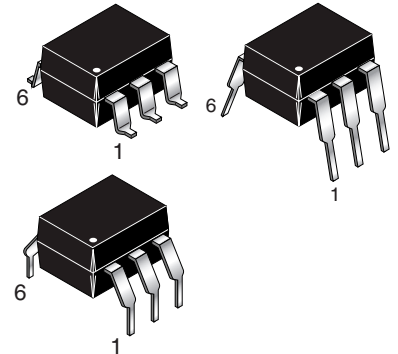
The MOC810X and CNY17F-X devices consist of a gallium arsenide LED optically coupled to a silicon phototransistor in a dual-in-line package.

- Closely Matched Current Transfer Ratio (CTR) Minimizes Unit-to-Unit Variation
- Narrow (CTR) Windows that Translate to a Narrow and Predictable Open Loop Gain Window
- Very Low Coupled Capacitance along with No Chip to Pin 6 Base Connection for Minimum Noise Susceptibility

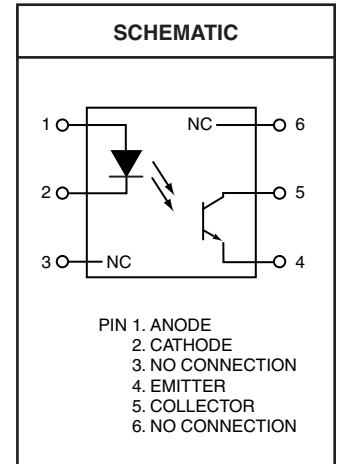
• To order devices that are tested and marked per VDE 0884 requirements, the suffix “.300” must be included at the end of part number. e.g. MOC8101.300 VDE 0884 is a test option.

APPLICATIONS

- Switchmode Power Supplies (Feedback Control)
- AC Line/Digital Logic Isolation
- Interfacing and coupling systems of different potentials and impedances



ABSOLUTE MAXIMUM RATINGS (T _A =25°C Unless otherwise specified)			
Parameter	Symbol	Value	Unit
INPUT LED			
Forward Current - Continuous	I _F	100	mA
Forward Current - Peak (PW = 1μs, 300pps)	I _{F(pk)}	1	A
Reverse Voltage	V _R	6	Volts
LED Power Dissipation @ T _A = 25°C	P _D	140	mW
Derate above 25°C		1.33	mW/°C
OUTPUT TRANSISTOR			
Collector-Emitter Voltage	V _{CEO}	70	Volts
MOC8106/7/8, CNY17F-1/2/3/4		30	
Emitter-Collector Voltage	V _{ECO}	7	Volts
Detector Power Dissipation @ T _A = 25°C	P _D	200	mW
Derate above 25°C		2.67	
TOTAL DEVICE			
Input-Output Isolation Voltage ⁽¹⁾ (f = 60 Hz, t = 1 min.)	V _{ISO}	5300	Vac(rms)
Total Device Power Dissipation @ T _A = 25°C	P _D	260	mW
Derate above 25°C		2.94	
Ambient Operating Temperature Range	T _{OPR}	-55 to +100	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Lead Soldering Temperature (1/16" from case, 10 sec. duration)	T _{SOL}	260	°C



NOTE

1. Input-Output Isolation Voltage, VISO, is an internal device dielectric breakdown rating.

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TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified)						
AC Characteristic	Test Conditions	Symbol	Min	Typ**	Max	Unit
NON-SATURATED SWITCHING TIME						
Turn-on Time	CNY17F-1/2/3/4 Only ($R_L = 100\ \Omega$, $I_C = 2\ \text{mA}$)	t_{on}	—	2	10	μs
Turn-off Time	CNY17F-1/2/3/4 Only ($V_{CC} = 10\ \text{V}$)	t_{off}	—	3	10	
Turn-On Time	All Devices ($I_C = 2.0\ \text{mA}$, $V_{CC} = 10\ \text{V}$, $R_L = 100\ \Omega$) ⁽³⁾	t_{on}	—	2	—	μs
Turn-Off Time	All Devices ($I_C = 2.0\ \text{mA}$, $V_{CC} = 10\ \text{V}$, $R_L = 100\ \Omega$) ⁽³⁾	t_{off}	—	3	—	
Rise Time	All Devices ($I_C = 2.0\ \text{mA}$, $V_{CC} = 10\ \text{V}$, $R_L = 100\ \Omega$) ⁽³⁾	t_r	—	1	—	μs
Fall Time	All Devices ($I_C = 2.0\ \text{mA}$, $V_{CC} = 10\ \text{V}$, $R_L = 100\ \Omega$) ⁽³⁾	t_f	—	2	—	
SATURATED SWITCHING TIMES						
Turn-on Time	CNY17F-1 ($I_F = 20\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)	t_{on}	—	—	5.5	μs
	CNY17F-2 CNY17F-3 CNY17F-4 ($I_F = 10\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)		—	—	8.0	
Rise Time	CNY17F-1 ($I_F = 20\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)	t_r	—	—	4.0	μs
	CNY17F-2 CNY17F-3 CNY17F-4 ($I_F = 10\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)		—	—	6.0	
Turn-off Time	CNY17F-1 ($I_F = 20\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)	t_{off}	—	—	34	μs
	CNY17F-2 CNY17F-3 CNY17F-4 ($I_F = 10\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)		—	—	39	
Fall Time	CNY17F-1 ($I_F = 20\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)	t_f	—	—	20	μs
	CNY17F-2 CNY17F-3 CNY17F-4 ($I_F = 10\ \text{mA}$, $V_{CE} = 0.4\ \text{V}$)		—	—	24	

** All typicals at $T_A = 25^\circ\text{C}$

NOTES:

1. Always design to the specified minimum/maximum electrical limits (where applicable).
2. Current Transfer Ratio (CTR) = $I_C/I_F \times 100\%$.
3. For test circuit setup and waveforms, refer to Figure 7.
4. For this test, Pins 1 and 2 are common, and Pins 4 and 5 are common.

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TYPICAL PERFORMANCE CURVES

Fig. 1 LED Forward Voltage vs. Forward Current

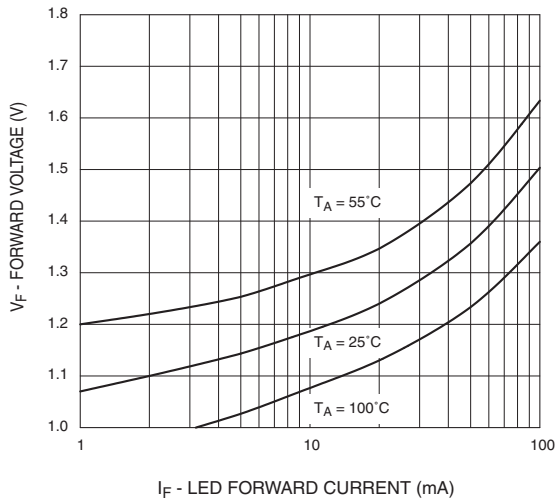


Fig. 2 Normalized CTR vs. Forward Current

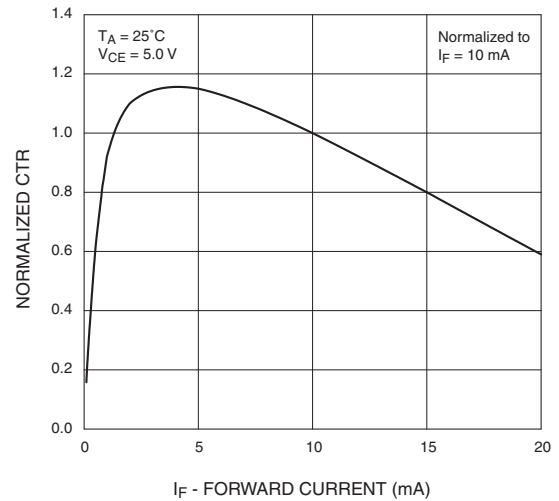


Fig. 3 Normalized CTR vs. Ambient Temperature

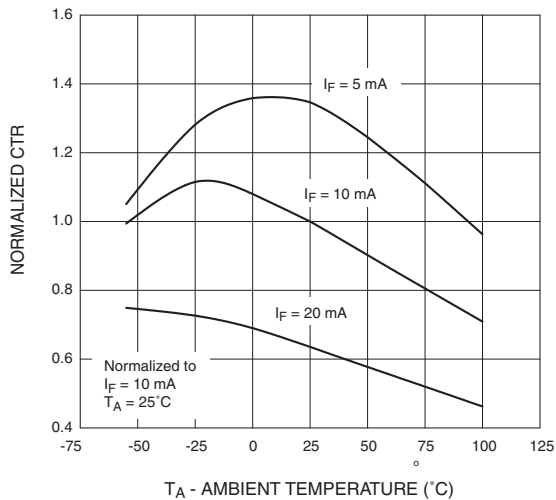
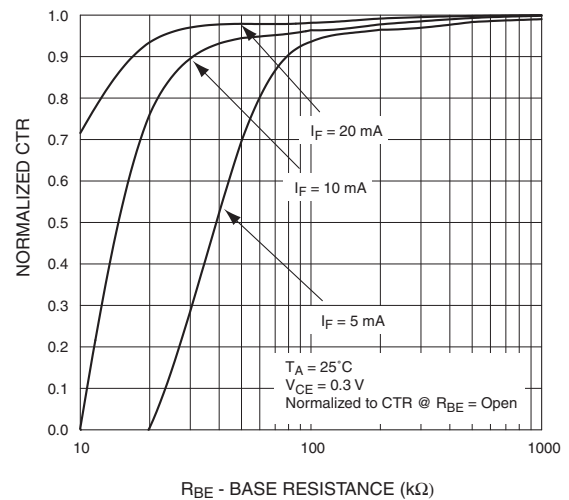


Fig. 4 CTR vs. R_{BE} (Saturated)



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Fig. 5 CTR vs. R_{BE} (Unsaturated)

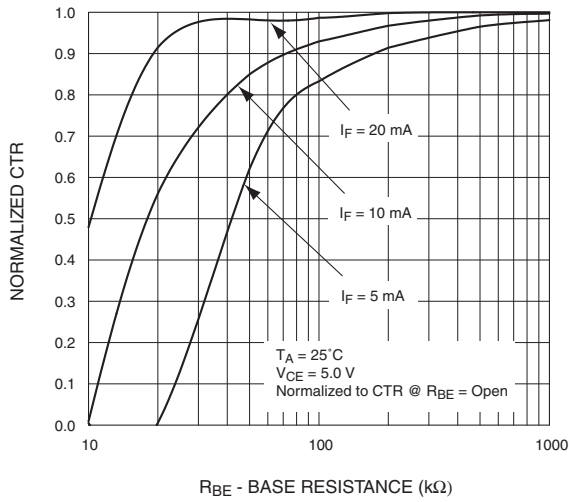


Fig. 6 Collector Emitter Saturation Voltage vs Collector Current

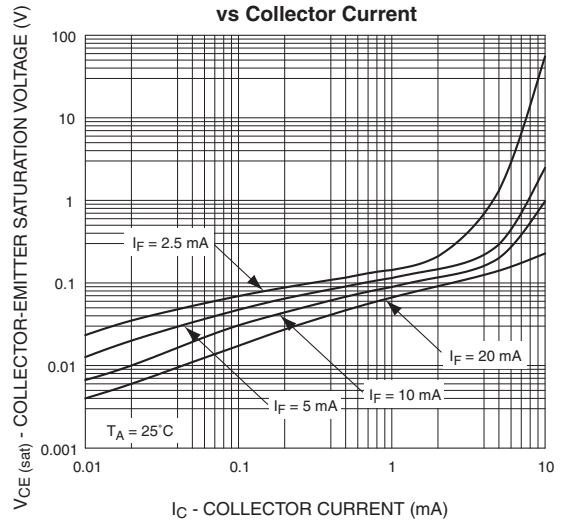


Fig. 7 Normalized t_{on} vs. R_{BE}

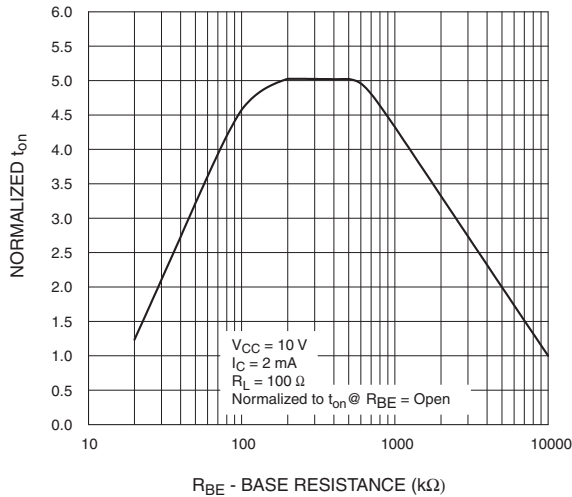
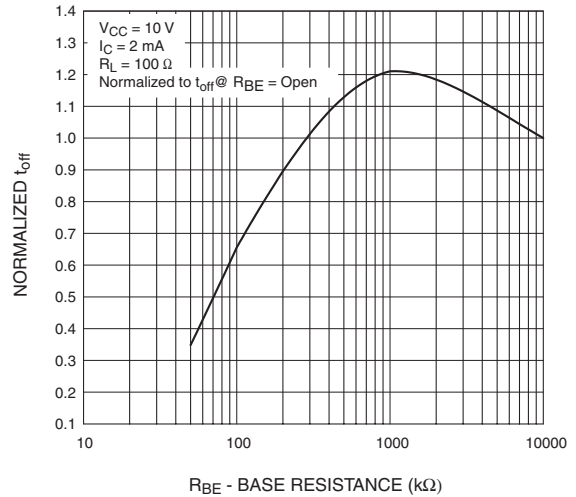


Fig. 8 Normalized t_{off} vs. R_{BE}



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Fig. 9 Switching Speed vs. Load Resistor

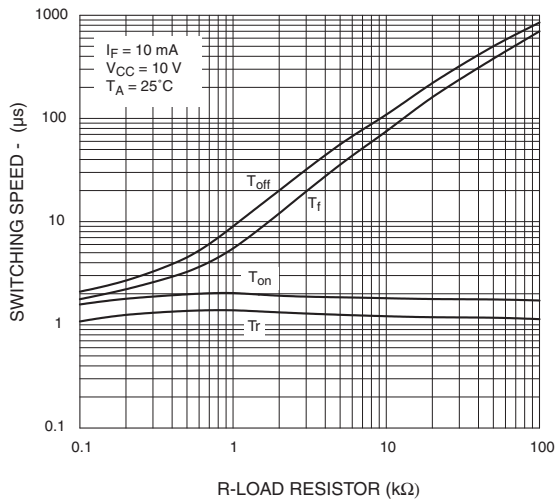
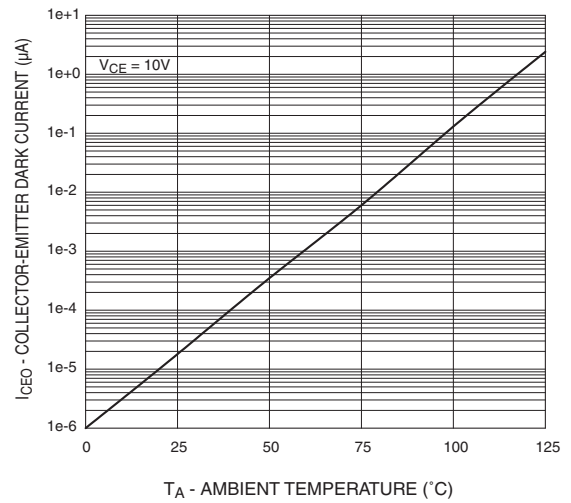
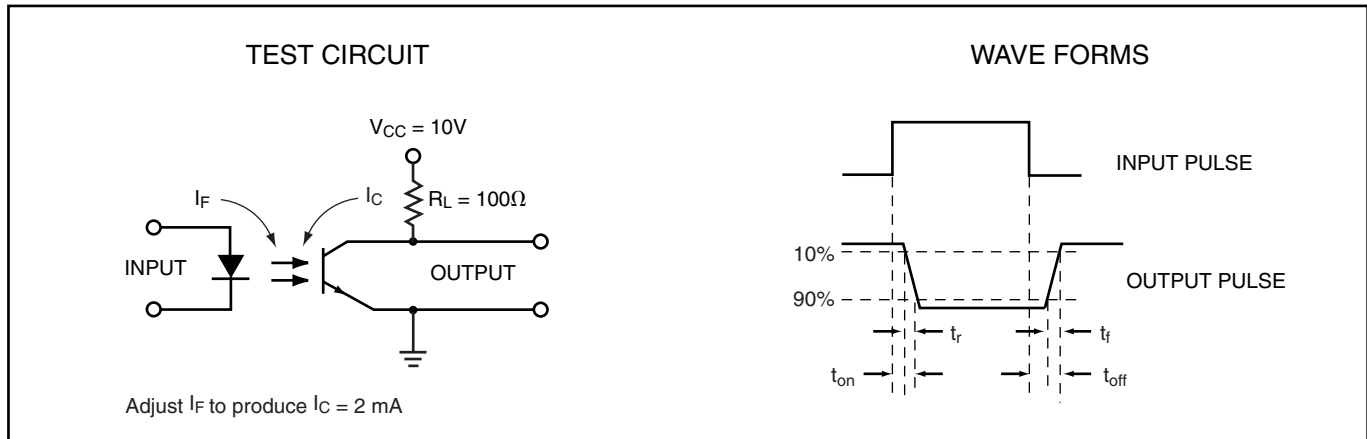


Fig. 10 Dark current vs. Ambient Temperature.



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Figure 7. Switching Time Test Circuit and Waveforms



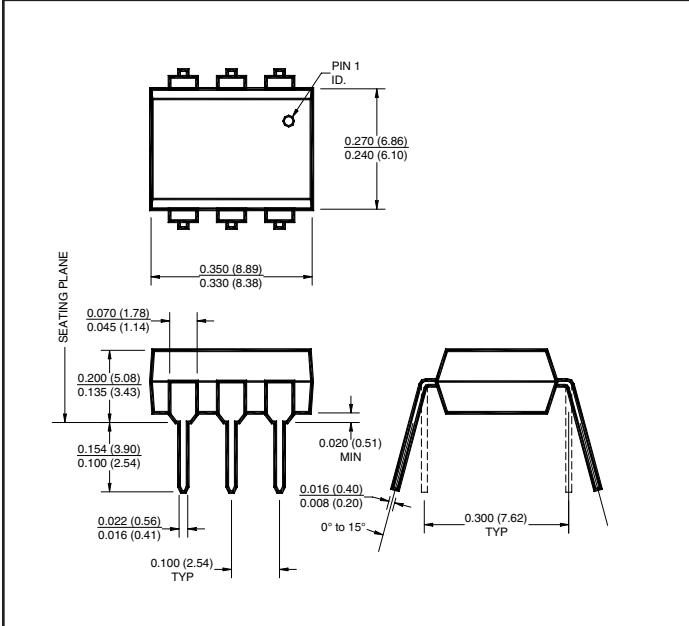
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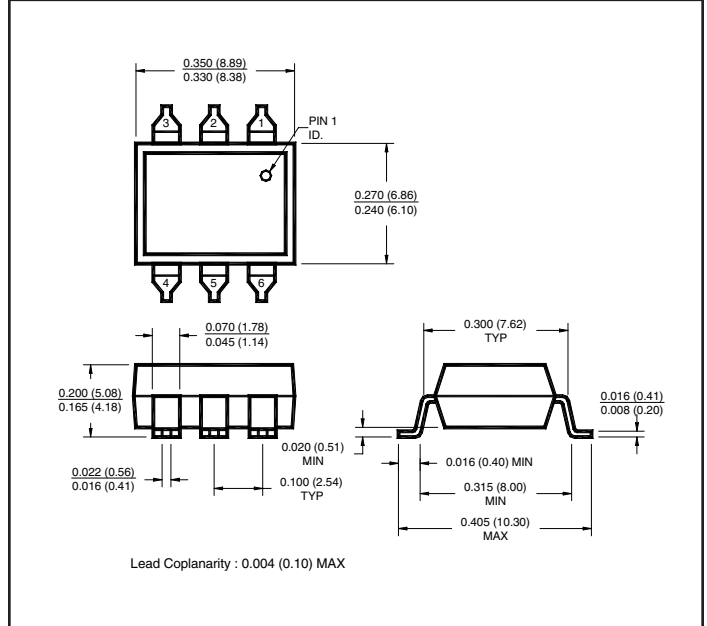
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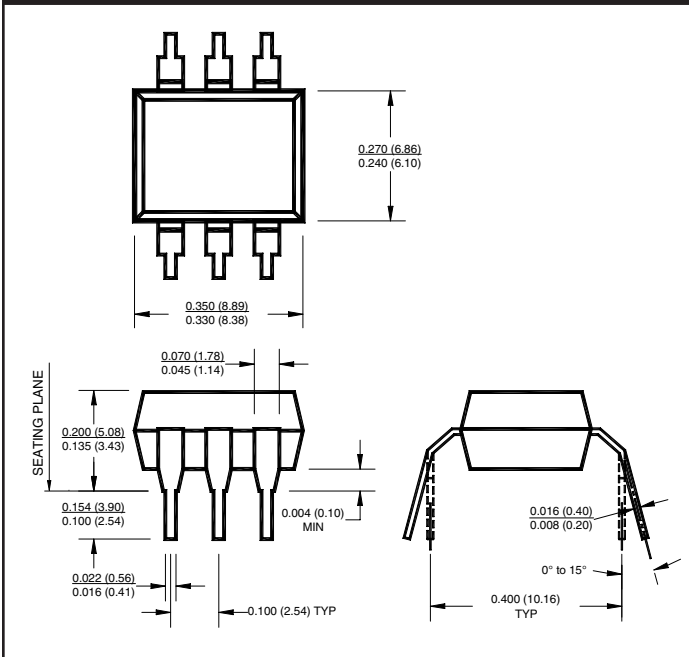
Package Dimensions (Through Hole)



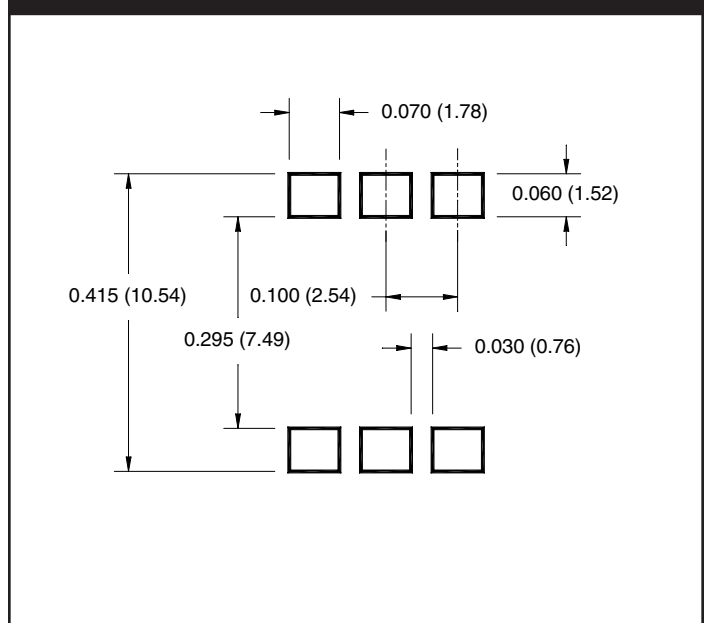
Package Dimensions (Surface Mount)



Package Dimensions (0.4" Lead Spacing)



**Recommended Pad Layout for
Surface Mount Leadform**



NOTE

All dimensions are in inches (millimeters)

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